1-2199119-6 V ACTIVE

M.2 NGFF

TE Internal #: 1-2199119-6

3.2 mm [.126 in] Height, M Code, Gold (Au), Power, -40 – 80 °C [-40

– 176 °F], M.2 NGFF, M.2 Connectors

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Connectors > PCB Connectors > Card Edge Connectors > M.2 Connectors > M.2 Connectors



Connector Height: 3.2 mm [.126 in]

Connector & Keying Code: M

Contact Mating Area Plating Material: Gold (Au)

Circuit Application: Power

Operating Temperature Range: -40 - 80 °C [-40 - 176 °F]

All M.2 Connectors (29)

Features

Product Type Features

Contact Base Material

PCB Contact Termination Area Plating Material

PCB Contact Termination Area Plating Material Finish

Product Type Features	
Connector & Contact Terminates To	Printed Circuit Board
Connector System	Board-to-Board
Configuration Features	
Number of Positions	67
PCB Mount Orientation	Right Angle
Number of Rows	2
Electrical Characteristics	
Operating Voltage	50 VAC
Body Features	
Primary Product Color	Black
Connector & Keying Code	M
Contact Features	
Contact Current Rating (Max)	.5 A

Copper Alloy

Gold Flash, Tin

Matte

30 µin



Contact Mating Area Plating Material	Gold (Au)
Termination Features	
Termination Method to PCB	Surface Mount
Mechanical Attachment	
Connector Mounting Type	Board Mount
Housing Features	
Housing Material	High Temperature Thermoplastic
Centerline (Pitch)	.5 mm[.02 in]
Dimensions	
Connector Width	8.7 mm[.343 in]
Connector Length	21.9 mm[.862 in]
Connector Height	3.2 mm[.126 in]
Usage Conditions	
Operating Temperature Range	-40 - 80 °C[-40 - 176 °F]
Operation/Application	

Packaging Features

Circuit Application

Packaging Method Tape & Reel

Power

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2025 (247) Candidate List Declared Against: JAN 2025 (247) Does not contain REACH SVHC
Halogen Content	Low Bromine/Chlorine - Br and Cl < 900 ppm per homogenous material. Also BFR /CFR/PVC Free
Solder Process Capability	Reflow solder capable to 260°C



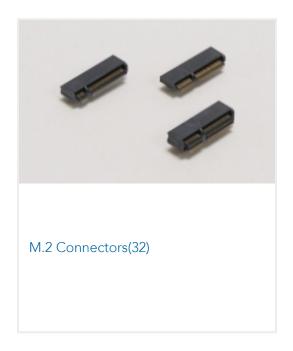
Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts



Also in the Series M.2 NGFF



Customers Also Bought









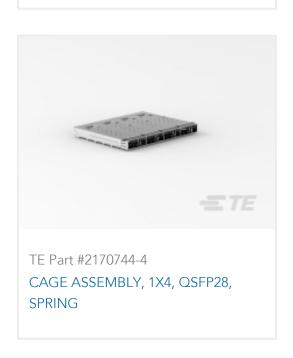












Documents

Product Drawings

M.2 0.5PITCH 3.2H KEY M 30U" AU

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_1-2199119-6_C.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_1-2199119-6_C.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_1-2199119-6_C.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Datasheets & Catalog Pages

1-1773702-1_NGFF_QRG-EN

English

Product Specifications

Application Specification

English